Korean International Semiconductor Conference & Exhibition
on Manufacturing Technology 2025

KISM 2025 BUSAN

Re:Innovation of Semiconductor Manufacturing for AI Ecosystem

[WeF1] Processing for AI Semiconductor Modules

Session Date	November 12 (Wed.), 2025
Session Time	09:00-10:35
Session Room	Room F (Panorama Room, 16F)
Session Chair	Prof. Hongyun So (Hanyang Univ., Korea)

[WeF1-1] [Plenary] **09:00-09:45**

Status of AI Packages and Its Manufacturing Issues

Seungbae Park (State Univ. of New York at Binghamton, USA)

[WeF1-2] [Invited] **09:45-10:15**

Challenges of Hybrid Cu Bonding for High Bandwidth Memory

Jaewha Park, Byengjun Lee, Ilyoung Yoon, Cheolhyun Lim, and Kwangjin Moon (Samsung Electronics Co., Ltd., Korea)

[WeF1-3] [Invited] **10:15-10:35**

Cu Post Bonding Technology, based on Laser-Assisted Bonding with Compression (LABC) and Fume-Free Laser Solder Paste for Advanced 3D Interconnections

Kwang-Seong Choi, Jiho Joo, Gwang-Mun Choi, Jungho Shin, Chanmi Lee, Ki-Seok Jang, Jin-Hyuk Oh, Ho-Gyeong Yun, Seok Hwan Moon, Gaeun Lee, Seong Cheol Kim, Yong-Sung Eom (ETRI, Korea), Geunsik Ahn, and Youn Sung Ko (PROTEC Co., Ltd., Korea)